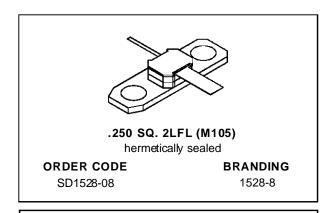
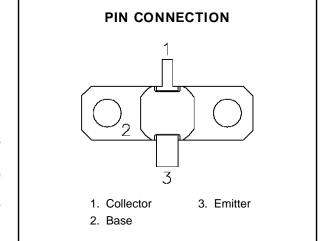


SD1528-08

RF & MICROWAVE TRANSISTORS AVIONICS APPLICATIONS

- DESIGNED FOR HIGH POWER PULSED IFF, DME, TACAN APPLICATIONS
- 20 WATTS (typ.) IFF 1030 1090 MHz
- 15 WATTS (min.) DME 1025 1150 MHz
- 15 WATTS (typ.) TACAN 960 1215 MHz
- 10 dB MIN. GAIN
- REFRACTORY GOLD METALLIZATION
- EMITTER BALLASTING AND LOW THERMAL RESISTANCE
- 20:1 LOAD VSWR CAPABILITY AT SPECIFIED OPERATING CONDITIONS
- INPUT MATCHED, COMMON BASE CONFIGURATION





DESCRIPTION

The SD1528-08 is a gold metallized, silicon NPN power transistor. The SD1528-08 is designed for applications requiring high peak power and low duty cycles such as IFF, DME and TACAN. The SD1528-08 is packaged in the .250" input matched hermetic stripline flange package resulting in improved broadband performance and a low thermal resistance.

ABSOLUTE MAXIMUM RATINGS $(T_{case} = 25^{\circ}C)$

Symbol	Parameter	Value	Unit	
V _{CBO}	Collector-Base Voltage	65	V	
V _{CEO}	Collector-Emitter Voltage	65	V	
V _{EBO}	Emitter-Base Voltage	3.5	V	
Ic	Device Current	1.5	А	
P _{DISS}	Power Dissipation	87.5	W	
TJ	Junction Temperature	+200	°C	
T _{STG}	Storage Temperature	- 65 to +150	°C	

THERMAL DATA

R _{TH(j-c)} Junction-Case Thermal Resistance	2.0	°C/W
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SD1528-08

ELECTRICAL SPECIFICATIONS (Tcase = 25°C)

STATIC

Symbol	Test Conditions	Value			Unit		
		Min.	Тур.	Max.			
ВУсво	I _C = 10mA	$I_E = 0mA$		65		_	V
BVces	I _C = 25mA	$V_{BE} = 0V$		65			V
BV _{EBO}	I _E = 1mA	$I_C = 0mA$		3.5		_	V
I _{CES}	V _{CE} = 50V	$I_E = 0mA$		_		2	mA

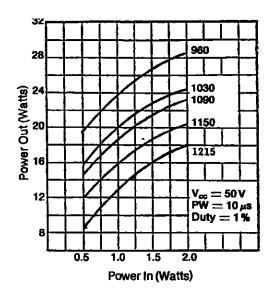
DYNAMIC

Symbol	Test Conditions		Value		
			. Typ.	Max.	Unit
Pout	f = 1025 — 1150MHz P _{IN} = 1.5 W V _{CE} = 50	V 15	_	_	W
G _P	f = 1025 — 1150MHz P _{IN} = 1.5 W V _{CE} = 50	V 10	_	_	dB
ης	f = 1025 — 1150MHz P _{IN} = 1.5 W V _{CE} = 50	V 30	_	_	%

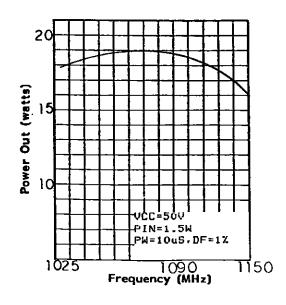
Note: Pulse Width = $10\mu Sec$, Duty Cycle = 1%

TYPICAL PERFORMANCE

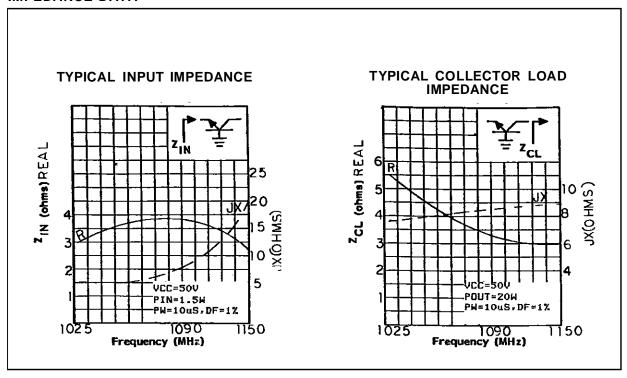
POWER OUTPUT vs POWER INPUT



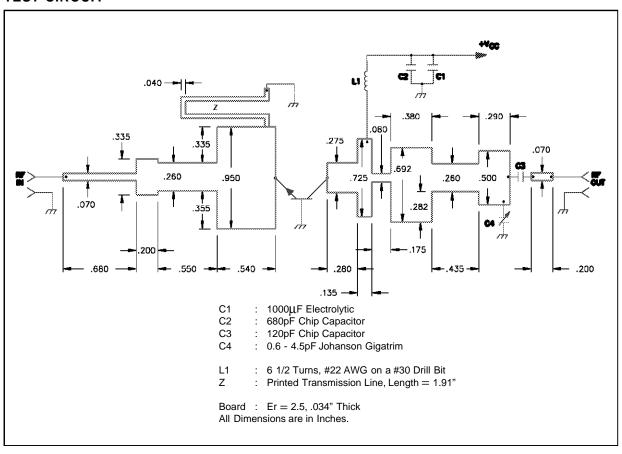
POWER OUTPUT vs FREQUENCY



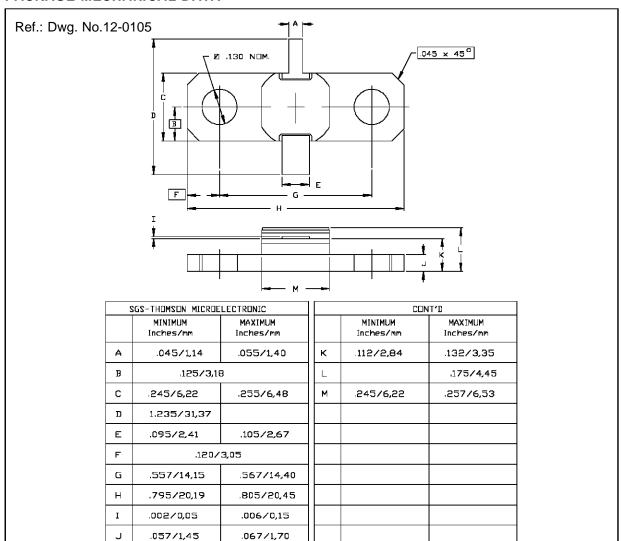
IMPEDANCE DATA



TEST CIRCUIT



PACKAGE MECHANICAL DATA



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